2X ⌓ 0.15

A1 INDEX AREA

21

B

(8.54)

C

D

624X ⌓ 0.20 A

A

SEATING PLANE

⫽ 0.2 A

5

4

(7.39)

21

2X ⌓ 0.15

D

TOP VIEW

19.2

24X 0.8

UNDERFILL 3MM MAX

AE AD AC AB AA Y W V U T R P N M L K J H G F E D C B A

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25

24X 0.8

19.2

624X ⌀0.5±0.05

3

⌖	⌀0.15 Ⓜ	A	B	C
	⌀0.08 Ⓜ	A		

SOLDER BALLS

A1 INDEX AREA

BOTTOM VIEW

0.4±0.1

0.66±0.1

1.05±0.11

1.45±0.15

VIEW D–D

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TITLE: FC PBGA, NO LID 21 X 21 X 1.45 PKG, 0.8 MM PITCH, 624 I/O	DOCUMENT NO: 98ASA00830D	REV: A
	STANDARD: JEDEC MS-034	
	SOT1642-2	14 JAN 2016

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M—1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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